



Media Release

NANIUM and UTAC Collaborate On Turnkey Backend Solutions for Wafer Level Packaging and Testing

Porto / Singapore, 6 April 2016 – NANIUM, S.A. (NANIUM), a Portugal-based semiconductor manufacturing, test and engineering services provider and UTAC Holdings Ltd (UTAC), a Singapore-based semiconductor assembly and test services provider, signed a collaborative agreement to provide a complete turnkey backend solution for Wafer Level Packaging (WLP) solutions.

The collaboration will enable NANIUM and UTAC to offer customers a full turnkey solution comprising of NANIUM's full suite of Wafer Level Packaging / Bumping Services including both Fan-in (WLCSP) and Fan-out (FOWLP) single chip, multi-chip or SIP wafer level processing, complemented by UTAC's backend assembly and test services.

"NANIUM is an industry leader in WLP with an extensive track record and IP portfolio in Wafer Level Packaging / Bumping Services. Through this collaboration, we will be able to offer joint customers a seamless solution comprising NANIUM's superior solutions and UTAC's assembly and test capabilities spread across a wide manufacturing base in Asia," said Mr. Asif Chowdhury, UTAC Senior Vice President of Product Line & Marketing.

"UTAC has well proven test capabilities and test engineering expertise coupled with a strong base of more than 1600 test platforms available in Asia. This collaboration will allow NANIUM to offer full turnkey WLP / Bumping Services to its customers worldwide, combining NANIUM's WLP expertise with UTAC's strong Test know-how and capacity." said Mr. Paulo Queiroz, NANIUM's Management Board Member.

The demand for wafer level processing remains strong in the analog, digital and logic areas, and is being more widely adopted by CMOS image sensor and MEMS devices. According to research house Yole Development (2015), the overall WLP market is projected to grow at a compound average growth rate of 9%, and the FOWLP (a subset) is predicted to have a 30% compound average growth rate 2016 to 2020.

About NANIUM S.A.

NANIUM is a world-class provider of semiconductor assembly, packaging, test, engineering and manufacturing services. The company started as Siemens Semiconductors back in 1996 and nowadays is a leader in 300mm Wafer-Level Packaging (WLP), both Fan-In/WLCSP and Fan-Out/eWLB. NANIUM offers in-house capabilities for the entire development chain, from design to multiple Wafer-Level Packaging technologies, and the flexibility to tailor and test solutions that respond to the most demanding customer requirements. The company is based near Porto, Portugal, and has an office in Dresden, Germany.

For more information, visit www.nanium.com or contact:

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About UTAC Holdings Ltd

UTAC Holdings Ltd (UTAC) is a leading independent provider of assembly and test services for a broad range of semiconductor chips and we offer a full range of semiconductor assembly and test services in the following key product categories: analog, mixed-signal and logic, and memory. Our customers are primarily fabless companies, integrated device manufacturers and wafer foundries. UTAC is headquartered in Singapore, with production facilities located in Singapore, Thailand, Taiwan, China, Indonesia and Malaysia, in addition to its global sales network focused on five regions: United States, Japan, China and Taiwan, rest of Asia and Europe, with sales offices located in each of these regions.

For more information, please visit www.utacgroup.com or contact:

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